

# AFE4300 Low-Cost, Integrated Analog Front-End for Weight-Scale and Body Composition Measurement

## 1 Features

- Weight-scale front-end:
  - Supports up to four load cell inputs
  - On-chip load cell 1.7-V excitation voltage for ratiometric measurement
  - 68-nVrms Input-Referred noise (0.1 Hz to 2 Hz)
  - Best-fit linearity: 0.01% of full-scale
  - Weight-scale measurement : 540  $\mu$ A
- Body composition front-end:
  - Supports up to three tetra-polar complex impedance measurements
  - 6-Bit, 1-MSPS sine-wave generation digital-to-analog converter (DAC)
  - 247.5- $\mu$ Arms,  $\pm$ 20% Excitation source
  - 0.1- $\Omega$  Measurement RMS noise in 2-Hz BW
  - Body composition measurement : 970  $\mu$ A
- Analog-to-digital converter (ADC):
  - 16 Bits, 860 SPS
  - Supply current: 110  $\mu$ A

## 2 Applications

Weight scales with body composition measurements

## 3 Description

The AFE4300 is a low-cost analog front-end incorporating two separate signal chains: one chain for weight-scale (WS) measurement and the other for body composition measurement (BCM) analysis. A 16-bit, 860-SPS analog-to-digital converter (ADC) is multiplexed between both chains. The weight measurement chain includes an instrumentation amplifier (INA) with the gain set by an external resistor, followed by a 6-bit digital-to-analog converter (DAC) for offset correction, and a circuit to drive the external bridge/load cell with a fixed 1.7 V for ratiometric measurements.

The AFE4300 can also measure body composition by applying a sinusoidal current into the body. The sinusoidal current is generated with an internal pattern generator and a 6-bit, 1-MSPS DAC. A voltage-to-current converter applies this sinusoidal current into the body, between two terminals. The voltage created across these two terminals as a result of the impedance of the body is measured back with a differential amplifier, rectified, and the amplitude is extracted and measured by the 16-bit ADC.

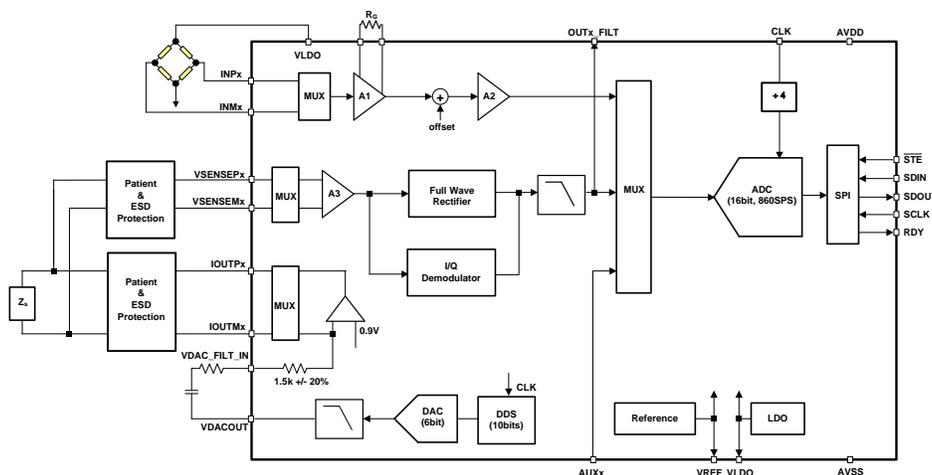
The AFE4300 operates from 2 V to 3.6 V, is specified from 0°C to +70°C, and is available in a LQFP-80 package.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
AFE4300	LQFP (80)	12.00 mm x 12.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Functional Block Diagram



## 4 Device and Documentation Support

### 4.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 4.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 4.3 Trademarks

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### 4.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 4.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">AFE4300PN</a>	Active	Production	LQFP (PN)   80	119   JEDEC TRAY (5+1)	Yes	NIPDAU	Level-3-260C-168 HR	0 to 70	AFE4300
AFE4300PN.A	Active	Production	LQFP (PN)   80	119   JEDEC TRAY (5+1)	Yes	NIPDAU	Level-3-260C-168 HR	0 to 70	AFE4300
<a href="#">AFE4300PNR</a>	Active	Production	LQFP (PN)   80	1000   LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 70	AFE4300
AFE4300PNR.A	Active	Production	LQFP (PN)   80	1000   LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 70	AFE4300

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

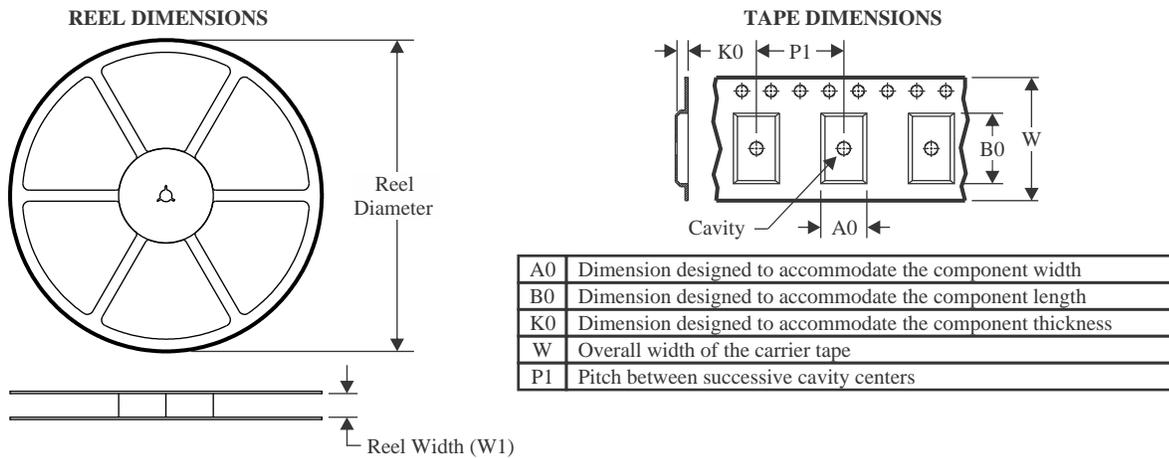
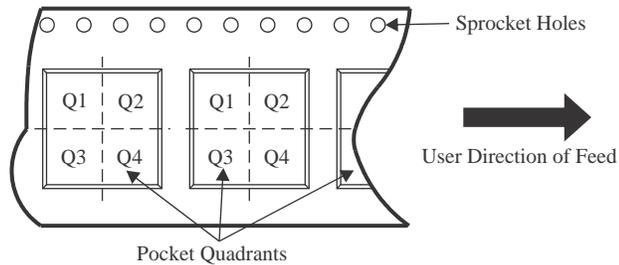
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

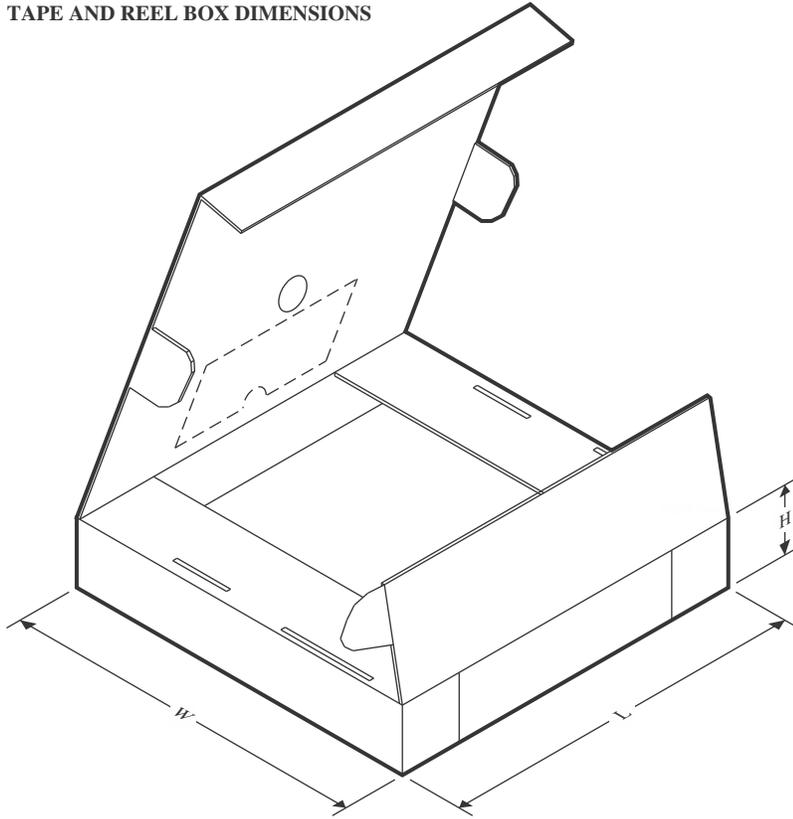
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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


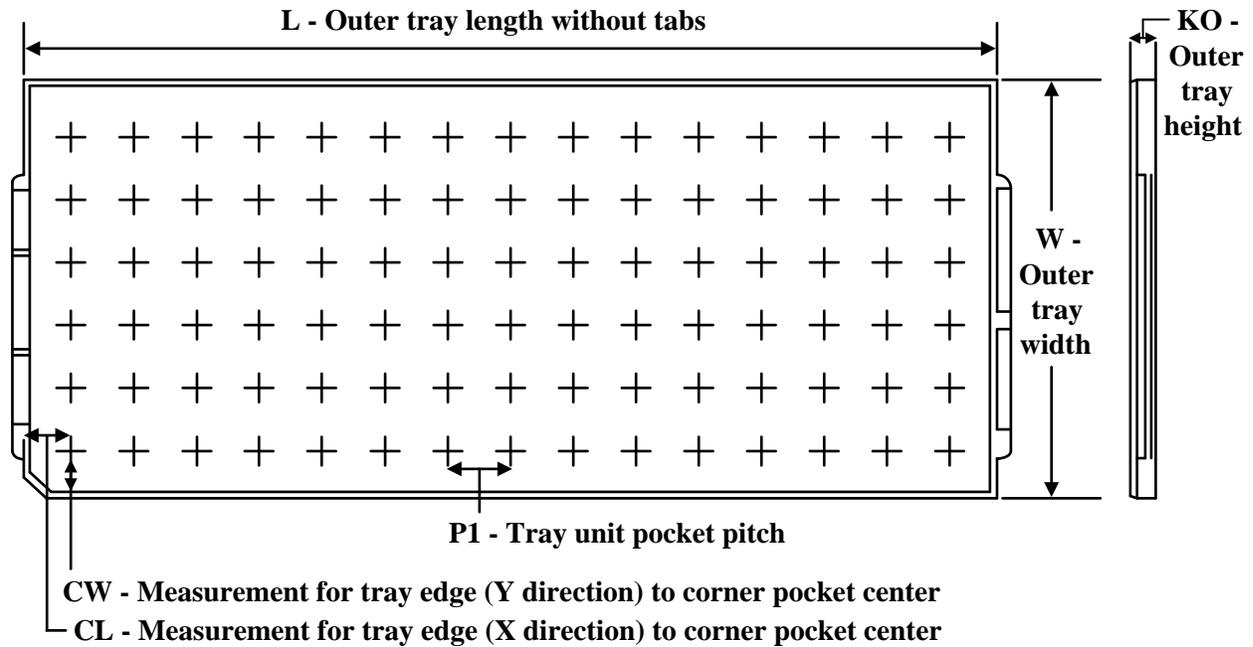
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AFE4300PNR	LQFP	PN	80	1000	330.0	24.4	16.0	16.0	2.0	24.0	24.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AFE4300PNR	LQFP	PN	80	1000	367.0	367.0	55.0

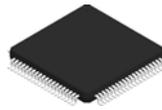
**TRAY**


Chamfer on Tray corner indicates Pin 1 orientation of packed units.

\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
AFE4300PN	PN	LQFP	80	119	7 X 17	150	315	135.9	7620	17.9	14.3	13.95
AFE4300PN.A	PN	LQFP	80	119	7 X 17	150	315	135.9	7620	17.9	14.3	13.95

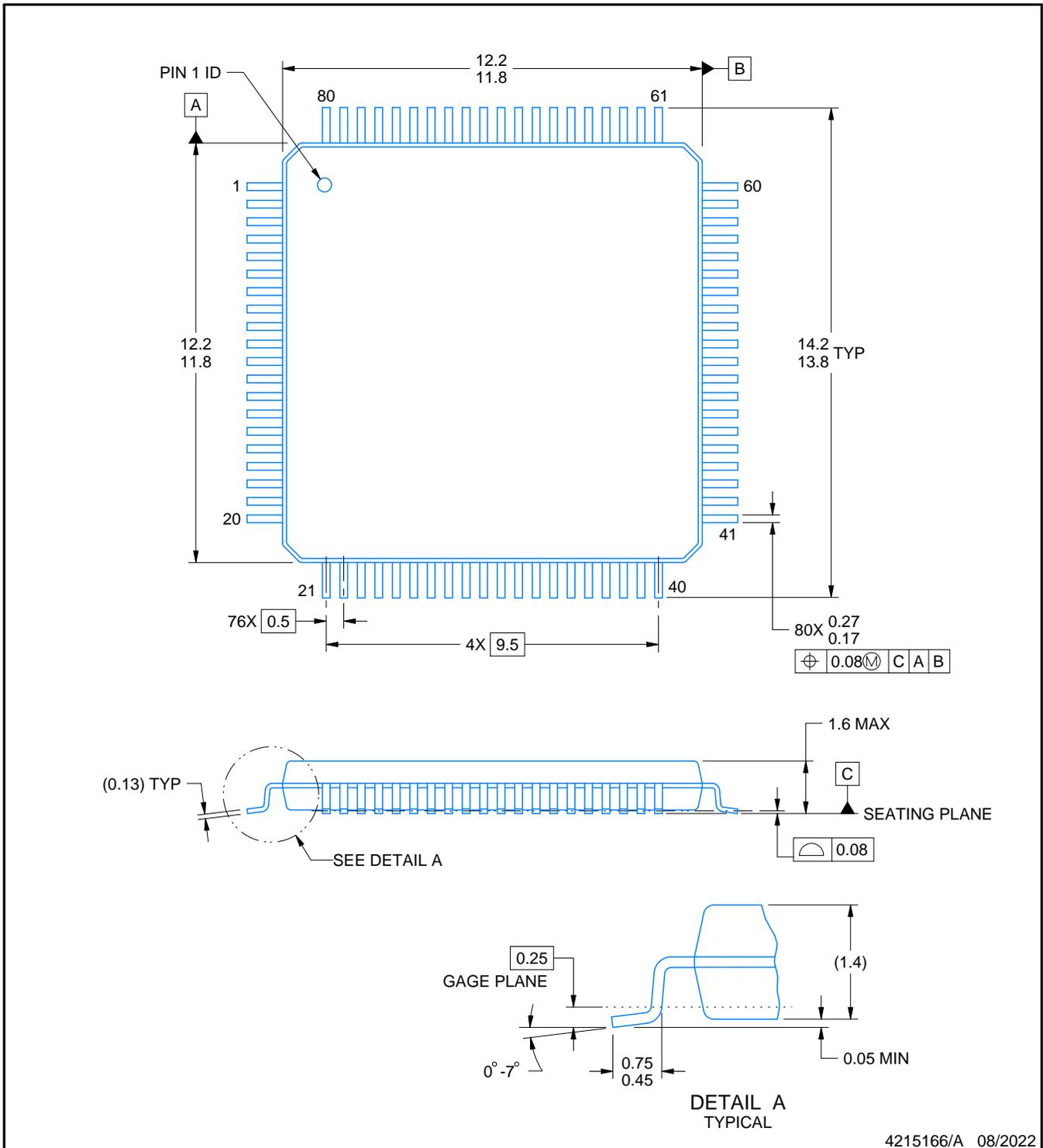
PN0080A



# PACKAGE OUTLINE

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES:

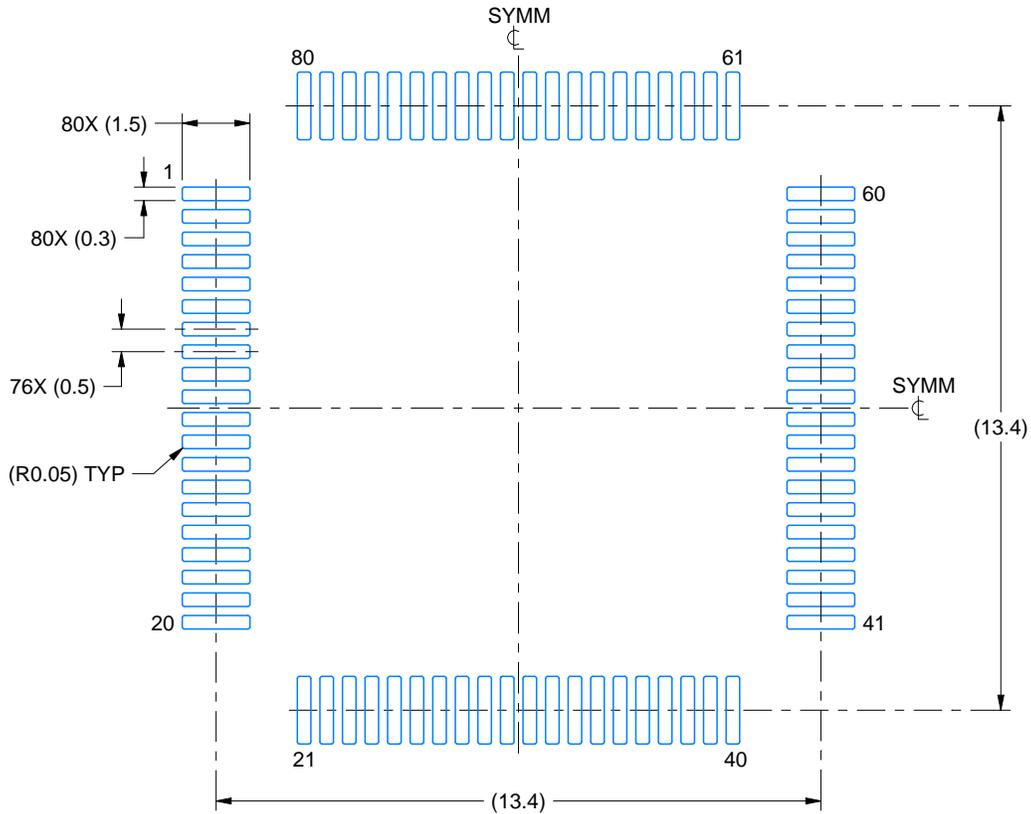
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MS-026.

# EXAMPLE BOARD LAYOUT

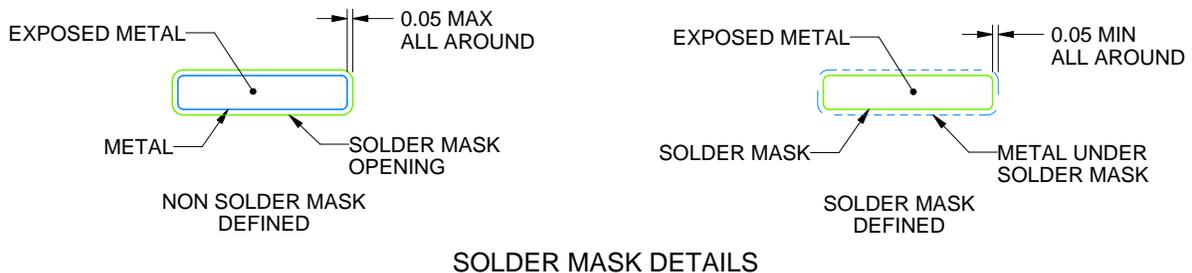
PN0080A

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

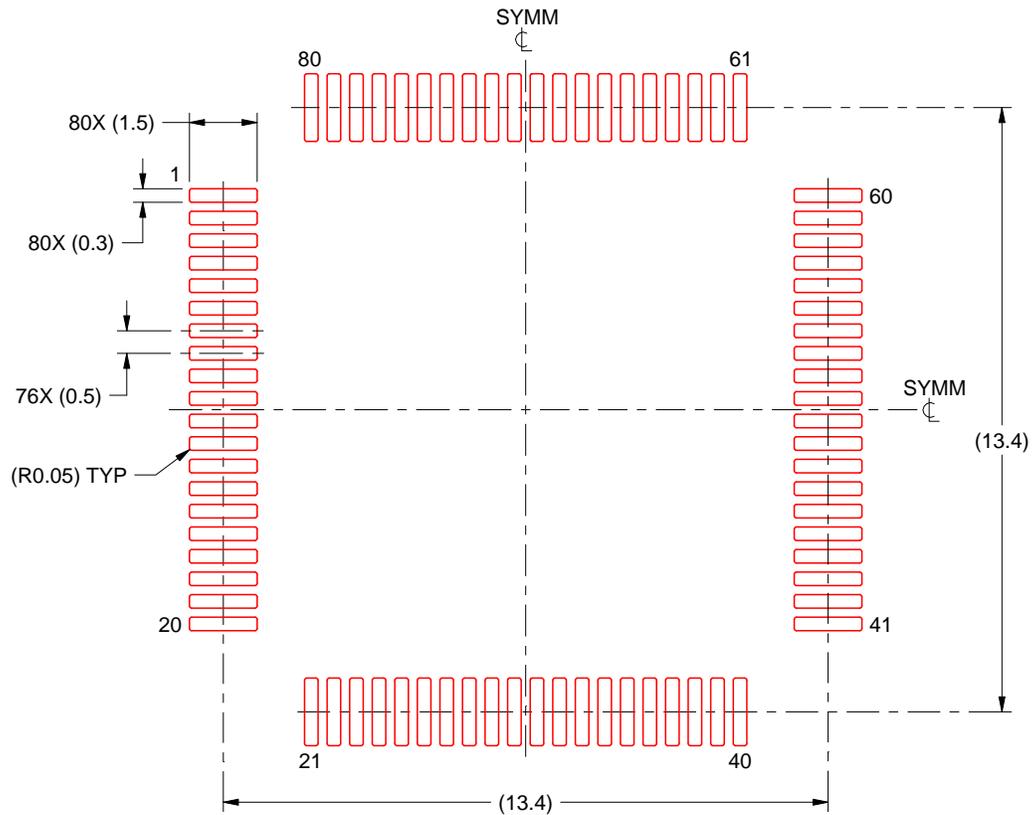
4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
6. For more information, see Texas Instruments literature number SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).

# EXAMPLE STENCIL DESIGN

PN0080A

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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